

MULTILAYER CERAMIC CAPACITORS

CAT. No. E1002M

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NIPPON CHEMI-CON

MULTILAYER CERAMIC CAPACITORS

Item	Series	Rated Voltage Range (Vdc)	Rated Capacitance Range(µF)	Temperature Characteristics	RoHS Compliant
Chip Type	(Upgrade!) NTS	25 to 250	0.033 to 33		
Chip Type	(Upgrade!) NTF	25 to 250	0.033 to 33	ΔC/C 25℃=±15%	Compliant
Metal cap Type	(Upgrade!) NTP	25 to 250	1.5 to 47	-55℃ to +125℃ (X7R : EIA)	Compliant
Lead Type	(Upgrade!) NTD	25 to 250	0.1 to 33		
Chip	THC	16 to 200	0.047 to 100		Compliant : Tin plating, Silver(THC) terminal *
Туре	тмс	25 to 200	0.033 to 10	ΔC/C 20°C=-55 to +20% -25°C to +85°C (E : JIS)	(Terminal code : N0,R0)
Metal cap	THP	16 to 200	0.45 to 200	ΔC/C 25℃=-56 to +22% -30℃ to +85℃ (Y5U : EIA)	Compliant : Silver plating terminal *
Туре	TMP	25 to 200	1.5 to 100	ΔC/C 25℃=-82 to +22% -55℃ to +125℃ (X7V : EIA)	(Terminal code : 5⊡)
Lead Type	THD	16 to 250	0.1 to 680		Compliant

* RoHS compliant types are recommended.

1 In designing device circuits

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- (1) Confirming the installation and operating environment of capacitors, use them within the rated performance limits prescribed in their catalog or product specifications. Otherwise, excessive use conditions cause the capacitors to have catastrophic failure such as short circuit, open circuit or firing.
- (2) Do not apply a DC voltage which exceeds the full rated voltage. The peak voltage of a superimposed AC voltage (ripple voltage) on the DC voltage must not exceed the full rated voltage.
- (3) By considering the temperature characteristic and the DC bias characteristic of the ceramic capacitors, please determine the right capacitance. The capacitance of the capacitors changes in low and high temperature ambiences and depends on the applied bias voltages. The capacitance change (i.e. reduction) may affect the performance of the circuit which is containing the capacitors. Therefore, please examine the capacitors in the actual operational conditions to verify that they are right ones.
- (4) The common failure mode of multilayer ceramic capacitors is contingent insulation breakdown or short circuit. When the capacitors are used in a high-power circuit, they may damage the surroundings of the capacitors when failed. Therefore, the high-power circuit should have protective device/protective devices to shut down the circuit from the capacitor/capacitors. The reliability of the capacitors improves when the ambient temperatures are in the normal temperature range and the applied voltages are low.
- (5) When large high frequency ripple current acrosses multilayer ceramic capacitor, the capacitor can vibrate. The phenomenon occurs as the capacitor, has natural vibration frequency due to the mechanical dimensions, resonates to the large high frequency ripple current.

To prevent the resonance, please select the capacitor or change the ripple current frequency.

For your information	, we indicate the	following resonance	frequency to e	ach chip size.
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Size Code NTS, NTF, NTP, NTD	Chip Size	(kHz)
31	3.2× 1.6	650, 1200, 1600
32	3.2× 2.5	650, 850, 1200
43	4.5× 3.2	450, 650, 1200
55	5.7× 5.0	350, 450, 850

Size	Code	Chin Cine	(kHz)		
THC,THP	THD	Chip Size			
21		2.0× 1.25	900, 1500, 1800		
31		3.2× 1.6	600, 1200, 1600		
32	32	3.2× 2.5	600, 750, 1200		
43	43	4.5× 3.2	400, 600, 1000		
55	55	5.7× 5.0	300, 400, 900		
76	76	7.5× 6.3	250, 350, 750		
	80	10.0× 9.0	160, 200, 600		
	90	20.0×12.7	90, 160, 500		
	99	25.0×12.7	75, 160, 300		

- (6) The capacitance of the capacitors depends on the ambient temperatures and bias voltages. Therefore, please examine the capacitors when they are to be used in a time-constant circuit before the use.
- (7) Consult us for devices that requires high reliability. For components which are used to the devices whose failure affects human life or causes social loss by serious damage, higher reliable designs than general purpose components are required.

2 In designing PC boards

- (1) Put the proper volume of solder (the size of fillet) on PC boards for installing surface mount capacitors, because it directly affects the installed capacitors. The design of copper pad patterns and dimensions should be set so that the proper volume of solder can be provided. The recommended land dimensions are shown below.
- (2) Land width of PC boards shall not exceed the width of chip capacitors.

Chip type						(mm)
Code Size Code	21	31	32	43	55	76
а	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5	2.5 to 3.5	2.7 to 4.7	3.8 to 5.0
b	3.0 to 4.6	4.2 to 5.8	4.2 to 5.8	5.5 to 6.1	6.7 to 8.3	8.8 to 10.8
С	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5	2.3 to 3.2	3.5 to 5.0	4.7 to 6.3
d	0.3 to 0.6	0.4 to 0.8	0.5 to 1.0	0.6 to 1.1	0.7 to 1.2	0.8 to 1.3



- (3) When the multilayer ceramic capacitors are mounted on a substrate, the chips may crack when mechanical stress is put. Also, when the substrate is bent, they may also crack. Therefore, please make sure that the material and size of the substrate and the capacitor positions are right.
- (4) For a leaded capacitor, design the PC boards with the correct terminal hole space equal to the lead space of the capacitor.

3 Installation

- (1) When installing leaded capacitors in the PC boards by means of an automatic insertion machine, minimize the mechanical shock applied to the capacitors by the lead clinch unit of the machine.
- (2) When the capacitors are to be mounted on a substrate, please minimize the shock and weight to the capacitor bodies. The nozzle pressure during the mounting process should be adjusted to 1N~3N maximum in static load.
- (3) Periodically maintain and inspect installation machines.
- (4) Where an adhesive is used to pre-anchor capacitors on PC boards, use appropriate copper pad dimensions,type of adhesive, coating volume, curing temperature and time, etc. to prevent the capacitors from deteriorating.

4 Soldering

- (1) Use flux with a halogen content of less than 0.1 wt. %. Do not use strong acid flux.
- (2) Minimize a volume of flux to coat the PC boards with.
- (3) Follow the soldering conditions prescribed in the catalog or product specifications. Excessive thermal stress affects the performance of the capacitors.
- (4) Note that surface mount capacitors with the size 3.2×1.6 or smaller tend to stand up during vapor phase reflow soldering.
- (5) For reflow soldering, place surface mount capacitors on the PC boards as soon as possible after solder paste was coated.
- (6) Please be aware that thermal deformation of substrates during mounting process cause stress to the substrates. Especially, substrates which are mounting chip capacitors are to be flow soldered to solder leaded parts or solder other parts onto the substrates, please make sure that the deformation during the soldering causes no harm. In fact, the deformation may cause stress to the substrates which leads to the capacitor element cracks/insulation-layer break down/insulation resistance degradation.The effect of the stress due to the deformation depends on the material of the substrates. Therefore, please be aware of the following information.
 - a) Ceramic substrates

The stress due to the deformation of ceramic substrates is thought be the minimum. Heat contract difference during solder hardening can be the effect to ceramic capacitors mounted on the substrates. So, please avoid forced cooling during the hardening.

b) Glass epoxy substrates

The stress due to the deformation and warp of glass epoxy substrates affects ceramic capacitors mounted. The stress depends on the size and material of the substrates, pattern positions and thermal gradient during soldering. Temperature difference between the both sides of the substrates may also cause the stress. When the material of the substrates, which are mounting ceramic capacitors, is FR-4 or the equivalent and other parts are to be flow soldered, the surface of the side with the capacitors shall be sufficiently preheated to 150° C or over before the flow soldering. During the soldering, the temperature difference between the side with the capacitors and the other side of the substrate should be 100° C maximum.

- c) Metal substrates The deformation and warp of metal substrates considerably affect ceramic capacitors mounted. Therefore, please use metal caps which can moderate the stress of the substrates.
- (7) After reflow/flow soldering, please cool the PC boards which mounted capacitors naturally in the air.
- (8) Ceramic chip capacitors are solderable by twice maximum in reflow or flow soldering. When the capacitors are to be reflow soldered and then flow soldered, there shall be no additional soldering to the capacitors. However, the capacitors having a size of 5.7×5.0 or larger should be soldered by one time only.
- (9) Due to the nature of ceramic, radical heating or cooling and partial heating may crack the ceramic capacitor element. Please have enough pre-heating process before soldering.
- (10)Ultrasonic cleaning time shall be ten minutes maximum.

When the power of ultrasonic cleaner is too high, the strength of terminations may drop.

Therefore, carefully examine the cleaning conditions before use.

- (11)Adjust the amount of solder cream in order that solder fillet shall be 1/2 to 2/3 height of chips. If fillet can confirm, size of 4.5×3.2 or larger is not this limit.
- (12)When more than two chips are mounted on a common land, please separate the chips by the solder resist.
- (13)In hand soldering, please take into consideration the following items.
 - 1. Fully pre-heat on a heating plate whose surface temperature is $100^\circ\!C$ to $150^\circ\!C$.
 - 2. Soldering iron power shall not exceed 30W.
 - 3. Soldering iron tip diameter shall not exceed 3mm.
 - 4. Temperature of iron tip shall be adjusted to not exceed 300℃.
 - 5. The soldering iron tip shall not touch ceramic body directly.

5 Soldering profile

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6 Cleaning

- (1) In the case that the assembly boards are washed, choose the appropriate cleaning agent for the washing purpose.
- (2) To determine the cleaning conditions, make sure by means of the actual washing equipment that the performance of the capacitors is not affected.
- (3) In the case that water-soluble flux was used, sufficiently wash the assembly boards.

7 Coating materials

- (1) When ceramic capacitors are to be resin coated or molded, please pay enough attention. Ceramic capacitors molded in resin, and please do not use it. There is fear to destroy a capacitor by stress to occur by the expansion / the shrinkage when resin stiffens. When a thermal expansion shrinkage coefficient in hardening uses big resin, coating in the resin which is soft with capacitors, please make that stress is added to capacitors small as much as possible.
- (2) Confirm that harmful resolution or formation gasses are not generated from the coating materials during the curing process or by spontaneously leaving the coated assembly boards.
- (3) If a coating material is cured at higher temperatures than the Category temperature of the capacitor, the exterior resin will deteriorate resulting in the capacitor damage.

8 Handling

- (1) When cutting off a multi-board to make individual units, curving or twisting the board may crack the capacitors. Appropriate tools should be used to cut it off.
- (2) Excessive mechanical shock to capacitors or their assembly boards may make the capacitors crack.
- (3) Use leaded capacitors without bending their lead wires as much as possible.
- (4) When ceramic capacitors are stored with no load, the capacitance reduces during the storage (named "aging characteristic"). As for the product that capacitance decreased, capacity recovers in an initial value by heat-treating it.
- (5) When the electrodes of the ceramic capacitors are made of silver, needle crystals may form on the electrodes in an ambience containing sulfur compounds.

9 Storage

- (1) Do not store and use capacitors in the following environment. Water or salt water splashes, dew wets or toxic gasses (hydrogen sulfide, sulfurous acid, chlorine, ammonium) fills, Vibration or mechanical shock exceeding the limits prescribed in the catalog or product specifications.
- (2) Do not store capacitors in places that direct sunlight pours down or dewy places.
- (3) Avoid high temperature and humidity. The storage conditions should be : Temperature=Lower than 40°C Humidity=Lower than 70% RH



MULTILAYER CERAMIC CAPACITORS PRECAUTIONS AND GUIDELINES

10 Catalogs

Specification in catalogs may be subject to change without notice. Performance test data in the catalogs show typical values, which are not assured in the catalogs.

For the details, refer to Guideline of notabilia for fixed multilayer ceramic capacitors for use in electronic equipment, EIAJ RCR-2335 issued by Electronic Industries Association of Japan.

Part Numbering System

NIPPON CHEMI-CON

The current parts numbering system is changed to new system for global coding. Your cooperation will be very much appreciated.

Multilayer Ceramic Capacitors



①Category



	code
Coelles	coue

Code	Series
TS	NTS
TF	NTF
TD	NTD
TP	NTP
HC	THC
MC	TMC
HD	THD
HP	THP
MP	TMP

⑤Rated capacitance code

③Rated voltage code

Significant digit (two columns) + index (one column)

Code	Rated voltage
160	16Vdc
250	25Vdc
500	50Vdc
101	100Vdc
201	200Vdc
251	250Vdc

Temperature characteristics code

	Code	Temp. character	Temp. Range	ΔC/C
	E	E	-25 to 85℃	-55 to 20%
	В	X7R	-55 to 125℃	±15%

Unit of capacitance with (pF), and a sign of capacitance expresses it in 3 characters. significant digit (two columns) + index (one column) unit : pF (Example 1μ F=100000pF)

[®]Capacitance tolerance code

Code	Tolerance
K	±10%
М	±20%
Z	-20 to +80%

\bigcirc Size code

Type : Onip		
Dimensions (L×W)		
2.0×1.25		
3.2×1.6		
3.2×2.5		
4.5×3.2		
5.7×5.0		
7.5×6.3		

Type : Radial Lead

21	
Code	Dimensions (L×W)
32	5.0×6.5(6.0)
43	6.5×7.0(6.5, 7.5)
55	7.5(8.0)×9.0
76	10.0×11.5
80	13.5×15.0
90	22.5×20.0
99	28.5×20.0

Type : Metal Cap								
Code	Dimensions (L×W							
43	4.8×3.5							
55	6.0×5.0 (5.3)							

76

7.8×6.6

Type · Metal Cap

21		•								
Codo	Terminal									
Code	Series	Elements	Note	Plating	RoHS					
BF	NTP	2	Size code 55	Tin	Compliant					
5A	THP	2	Size code 43 and 55	Silver	Compliant					
5B	THP	2	Size code 76	Silver	Compliant					
5E	TMP	2	Spring mechanism	Silver	Compliant					
2A *	THP	2	Size code 43 and 55	Solder	Non-compliant					
2B *	THP	2	Size code 76	Solder	Non-compliant					
2E *	TMP	2	Spring mechanism	Solder	Non-compliant					

Terminal code

Ту	Type : Chip								
Code Terminal									
	N0 Tin plating								
	N1	Tin plating Excellent temp. cycle							
	R0	Silver							
	S0 *	Solder plating							

Imaging code

Code	Taping
Т	Taping
В	In pieces

Output Supplement code

Type : Radial Lead

Code

A0

B0 C0

Code	Supplement
00	Standard

Terminal

Straight Lead (copper wire)

Straight Lead Crimped Lead

* RoHS compliant types are recommended.

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CHIP TYPE TAPING SPECIFICATION



			Dimensions (mm)										
Туре	Size Code	A ±0.1	В ±0.1	W ±0.3	F ±0.05	Е ±0.1	P1 ±0.1	P2 ±0.05	P0 ±0.1	φD ±0.1	T1 max.	T2 max.	
	21	1.45	2.5	8.0	3.5	1.75	4.0	2.0	4.0	1.5	0.6	1.5	
	31	1.9	3.5	8.0	3.5	1.75	4.0	2.0	4.0	1.5	0.6	1.5	
Chip	32	2.8	3.5	8.0	3.5	1.75	4.0	2.0	4.0	1.5	0.6	2.5	
type	43	3.65	4.95	12.0	5.5	1.75	8.0	2.0	4.0	1.5	0.6	2.8	
	55	5.5	6.25	12.0	5.5	1.75	8.0	2.0	4.0	1.5	0.6	2.8	
	76	6.85	8.05	16.0	7.5	1.75	12.0	2.0	4.0	1.5	0.6	3.0	
Metal cap type	43	3.8	5.2	12.0	5.5	1.75	8.0	2.0	4.0	1.5	0.6	6.0	
	55	5.3	6.4	16.0	7.5	1.75	8.0	2.0	4.0	1.5	0.6	6.0	
	76	6.9	8.2	16.0	7.5	1.75	12.0	2.0	4.0	1.5	0.6	7.5	

•REEL SPECIFICATIONS



Size	Dimensions (mm)									
Code	NTS	, NTF, THC,	NTP, THP, TMP							
Code	21, 31, 32	43, 55	76	43	55, 76					
φA	178±2	178±2	178±2	178±2	382±2					
φΒ	50min.	50min.	50min.	50min.	80min.					
φC	13±0.5	13±0.5	13±0.5	13±0.5	13±0.5					
φD	21±0.8	21±0.8	21±0.8	21±0.8	21±0.8					
Е	2±0.5	2±0.5	2±0.5	2±0.5	2±0.5					
W	9±0.5	13±0.5	17±0.5	13±0.5	17±0.5					
Т	1±0.5	1±0.5	1±0.5	1±0.5	1±0.5					
R	1.0	1.0	1.0	1.0	1.0					

NTS, NTF, THC, TMC Series quantity per reel (pcs. / reel)

Size Code	21	31	32	43	55	76
Quantity	3,000	3,000	1,600	800	800	500

Note : Above quantity may vary for rating of capacitor.

♦RADIAL LEAD TYPE TAPING SPECIFICATION

•THD, NTD Series

Available for 32, 43, 55, 76 sizes. Ammo Packaging.

Sizo Codo	Dimensio	ons H (mm)	Quantity per Packing
Size Code	Straight lead	Crimped lead	(pcs.)
32	23max.	25max.	
43	24max.	26max.	2,000
55	26max.	28max.	
76	29max.	30max.	1,500
76	29max.	30max.	1,500

														(mm)
Code	Р	P ₀	P1	P ₀ /2	F	W	W/2	М	Mo	H₀	φD٥	φd	t	Δh
	12.7	12.7	3.85	6.35	5.0	18.0	9.0	13.0	1.5	16.0	4.0	0.5	0.6	0
Dimensions (mm)	±1	±0.3	±0.7	±1.3	+0.8 -0.2	+1.0 -0.5	±0.5	±1	±1.5	min.	±0.2	±0.05	±0.2	±2

NTP, THP, TMP Series quantity per reel (pcs. / reel)

Size Code	43	55	76	
Quantity	500	2,000	1,200	

Note : Above quantity may vary for rating of capacitor.



MINIMUM ORDER QUANTITY

Please order by units of minimum order quantity.

♦Chip

Size code	Quantity (pcs)
21	300
31	300
32	200
43	100
55	50
76	50

♦Radial Lead

Size code	Quantity (pcs)
32	100
43	100
55	100
76	50
80	10
90	10
99	10

Metal Cap

Size code	Quantity (pcs)	
All size	100	

MULTILAYER CERAMIC CHIP CAPACITORS



♦FEATURES

- 1. Large capacitance by small size.
- 2. Excellent noise absorption.
- 3. High permissible ripple current capability.
- 4. NTF: Temperature cycle : 1,000 cycles.

APPLICATIONS

- 1. Smoothing circuit of DC-DC converters.
- 2. On-board power supplies.
- 3. Voltage regulators for computers.
- 3. Noise suppressor for various kinds of equipments.
- 4. High reliability equipments.

♦CONSTRUCTION



RATINGS

1. Category Temperature Range	-55 to +125°C
2. Rated Voltage Range	25, 50, 100, 250Vdc
3. Rated Capacitance Range	0.033 to 33µF
4. Rated Capacitance Tolerance	K (±10%) , M (±20%)
5. Temperature Characteristics	X7R
6. Rated Ripple Current	See No.5 on the following table

\$SPECIFICATIONS

No.	Items	Specification	Test Condition		
1	Withstand Voltage	No abnormality.	250% of rated voltage shall be applied for 5 seconds. (Only 250Vdc product : 475V)		
2	Insulation Resistance	100/CR(MΩ) or 4000(MΩ) whichever is less.	Rated voltage shall be applied for 60±5 seconds at temperature 25±2°C.		
3	Rated Capacitance	Within specified tolerance.	Cr≦10µF Cr>10µF		Cr>10µF
			Temperature	25±	_2℃
4	Dissipation Factor	5.0% maximum.	Frequency	1±0.1kHz	120±12Hz
			Voltage	1±0.2Vrms	0.5±0.2Vrms
5	Rated Ripple Current	Size code 31 32 43 55 Arms 0.3 0.5 1.0 2.0	10kHz~1MHz (sine curve) Ripple voltage Vp shall be less than the rated voltage.		



oHS

MULTILAYER CERAMIC CHIP CAPACITORS



♦SPECIFICATIONS

No.	Items	Specification	Test Condition		
6	Adhesion	No visible damage.	Substrate 5N (0.51kgf) for 10±1 seconds Capacitor		
7	Bend strength of the face plating	Appearance : No visible damage. ΔC/C : ±15%	The substrate shall be bend at a rate of 1mm/s for 5 seconds.		
8	Solderability	Min. 75% of surface of the termination shall be covered with new solder	Solder Temperature : 235±5°C Dipping Time : 2±0.5 sec. Solder : Eutectic solder containning Ag2.5 to 3wt%		
9	Resistance to Soldering Heat	Appearance : No visible damage. $\Delta C/C : \pm 15\%$ D.F. : To meet the initial specification. I.R. : To meet the initial specification.	Solder Temperature : 260±5°C Dipping Time : 2±0.5 seconds Solder : Eutectic solder containning Ag2.5 to 3wt%		
10	Temperature Cycle	Appearance : No visible damage. $\Delta C/C : \pm 15\%$ D.F. : To meet the initial specification. I.R. : To meet the initial specification.	StepTemperature (°C)(min.)1Min. Category temperature ±330±32Room temperature3 max.3Max. Category temperature ±330±34Room temperature3 max.For above temperature cycle.NTS : For 5 cyclesNTF : For 1000 cycles		
11	Humidity Load Life	Appearance : No abnormality. $\Delta C/C : \pm 15\%$ D.F. : 10% maximum I.R. : 25/CR(M Ω) or 1000(M Ω) whichever is less.	Temperature : $40\pm2^{\circ}$ CHumidity: 90 to 95%RHVoltage: Rated voltageTime: $500\pm^{24}_{0}$ hours		
12	Endurance	Appearance : No abnormality. $\Delta C/C : \pm 15\%$ D.F. : 10% maximum LR : 50/CP(MQ) or 1000(MQ)	Temperature : $85\pm 2^{\circ}$ Voltage : 200% of rated voltage.Time : $1000\pm_{0}^{48}$ hours		
		whichever is less.	Temperature : $125\pm3^{\circ}$ CVoltage : Rated voltageTime : $1000\pm_{0}^{48}$ hours		

*CR : Rated Capacitance(µF)





◆PART NUMBERING SYSTEM



NTS SERIES STANDARD RATINGS

Dimensions(mm) Rated voltage Rated Capacitance Maximum ripple current Previous Part Number Part Number (Vdc) (µF) (Arms) (Just for your reference) L w Tmax а KTS250B105M31N0T00 1.0 NTS30X7R1E105MT KTS250B155M31N0T00 3.2±0.2 1.6±0.2 0.5±0.3 NTS30X7R1E155MT 1.5 1.8 0.3 KTS250B225M31N0T00 NTS30X7R1E225MT 2.2 KTS250B335M32N0T00 NTS40X7R1E335MT 3.3 KTS250B475M32N0T00 2.5±0.3 4.7 3.2±0.4 2.6 0.6±0.3 0.5 NTS40X7R1E475MT 25 KTS250B685M32N0T00 NTS40X7R1E685MT 6.8 KTS250B106M43N0T00 NTS50X7R1E106MT 10 4.5±0.4 3.2±0.4 2.8 0.6±0.3 1.0 KTS250B156M43N0T00 NTS50X7R1E156MT 15 2.8 KTS250B226M55N0T00 22 NTS60X7R1E226MT 5.7±0.4 5.0±0.4 0.8±0.5 2.0 KTS250B336M55N0T00 33 3.0 NTS60X7R1E336MT KTS500B334M31N0T00 0.33 NTS30X7R1H334MT NTS30X7R1H474MT KTS500B474M31N0T00 0 47 3.2±0.2 1.6±0.2 1.8 0.5±0.3 0.3 KTS500B684M31N0T00 0.68 NTS30X7R1H684MT KTS500B105M31N0T00 1.0 NTS40X7R1H105MT KTS500B155M32N0T00 1.5 NTS40X7R1H155MT 32+04KTS500B225M32N0T00 50 22 25+0326 06+0305 NTS40X7R1H225MT KTS500B335M32N0T00 3.3 NTS40X7R1H335MT KTS500B475M43N0T00 4.7 NTS50X7R1H475MT 4.5±0.4 3.2±0.4 2.8 0.6±0.3 1.0 KTS500B685M43N0T00 6.8 NTS50X7R1H685MT KTS500B106M55N0T00 10 NTS60X7R1H106MT 5.7±0.4 5.0±0.4 2.8 0.8±0.5 2.0 KTS500B156M55N0T00 15 NTS60X7R1H156MT KTS101B104M31N0T00 0.1 NTS30X7R2A104MT KTS101B154M31N0T00 0.15 NTS30X7R2A154MT KTS101B224M31N0T00 NTS30X7R2A224MT 0.22 3.2 ± 0.2 1.6 ± 0.2 0.5 ± 0.3 0.3 1.8 KTS101B334M31N0T00 0.33 NTS30X7R2A334MT KTS101B474M31N0T00 0.47 NTS30X7R2A474MT KTS101B684M32N0T00 NTS30X7R2A684MT 0.68 KTS101B105M32N0T00 NTS40X7R2A105MT 1.0 100 KTS101B155M32N0T00 1.5 3.2±0.4 2.5±0.3 2.6 0.6±0.3 0.5 NTS40X7R2A155MT NTS40X7R2A225MT KTS101B225M32N0T00 2.2 NTS50X7R2A155MT KTS101B155M43N0T00 1.5 KTS101B225M43N0T00 2.2 NTS50X7R2A225MT 4.5 ± 0.4 3.2 ± 0.4 2.8 0.6 ± 0.3 1.0 KTS101B335M43N0T00 3.3 KTS101B475M43N0T00 4.7 KTS101B685M55N0T00 5.7±0.4 5.0±0.4 2.8 0.8±0.5 2.0 6.8 KTS251B333M31N0T00 0.033 NTS30X7R2E333MT KTS251B473M31N0T00 NTS30X7R2E473MT 0.047 32+021.6±0.2 1.8 05+0303 KTS251B683M31N0T00 NTS30X7R2E683MT 0.068 KTS251B104M31N0T00 NTS30X7R2E104MT 0.1 KTS251B154M32N0T00 NTS40X7R2E154MT 0.15 250 3.2±0.4 2.5±0.3 2.6 0.6±0.3 0.5 NTS40X7R2E224MT KTS251B224M32N0T00 0.22 KTS251B334M32N0T00 NTS40X7R2E334MT 0.33 KTS251B474M43N0T00 0.47 NTS50X7R2E474MT 4.5±0.4 3.2±0.4 2.8 0.6±0.3 1.0 KTS251B684M43N0T00 NTS50X7R2E684MT 0.68 KTS251B105M55N0T00 NTS60X7R2E105MT 1.0 5.7±0.4 5.0±0.4 0.8±0.5 2.8 2.0 KTS251B155M55N0T00 1.5 NTS60X7R2E155MT

DIMENSIONS

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♦NTF SERIES STANDARD RATINGS



-	Rated voltage	Rated Capacitance	Dimensions(mm)			Maximum ripple current	
Part Number	(Vdc)	(μF)	L	w	Tmax.	а	(Arms)
KTF250B105M31N1T00		1.0					
KTF250B155M31N1T00		1.5	3.2±0.2	1.6±0.2	1.8	0.5±0.3	0.3
KTF250B225M31N1T00		2.2					
KTF250B335M32N1T00		3.3					
KTF250B475M32N1T00	25	4.7	3.2±0.4	2.5±0.3	2.6	0.6±0.3	0.5
KTF250B685M32N1T00	25	6.8					
KTF250B106M43N1T00		10	4 5 + 0 4	2 2+0 4	20	0.6+0.2	1.0
KTF250B156M43N1T00		15	4.5±0.4	3.2±0.4	2.0	0.0±0.3	
KTF250B226M55N1T00		22	5 7 + 0 1	5 0±0 4	2.8	0.8+0.5	2.0
KTF250B336M55N1T00		33	5.7 ±0.4	5.0±0.4	3.0	0.0±0.0	2.0
KTF500B334M31N1T00		0.33					
KTF500B474M31N1T00		0.47	3 2+0 2	1 6+0 2	1.8	0.5+0.3	03
KTF500B684M31N1T00		0.68	0.220.2	1.0±0.2	1.0	0.010.0	0.0
KTF500B105M31N1T00		1.0					
KTF500B155M32N1T00	50	1.5					0.5
KTF500B225M32N1T00		2.2	3.2±0.4	2.5±0.3	2.6	0.6±0.3	
KTF500B335M32N1T00		3.3					
KTF500B475M43N1T00		4.7	4.5 ± 0.4	3.2±0.4	2.8	0.6±0.3	1.0
KTF500B685M43N1T00		6.8		0.2=0.1	2.0	0.020.0	
KTF500B106M55N1T00	-	10	5.7±0.4	5.0±0.4	2.8	0.8±0.5	2.0
KTF500B156M55N1T00		15					
KTF101B104M31N1T00		0.1			1.8	0.5±0.3	0.3
KTF101B154M31N1T00		0.15					
KTF101B224M31N1T00		0.22	3.2±0.2	1.6±0.2			
KTF101B334M31N1100		0.33					
KTF101B474M31N1100		0.47					
KTF101B684M31N1100	100	0.68					
KTF101B105W32N1100	100	1.0	2 2 4 0 4	25+0.2	2.0	0.0+0.2	0.5
KTF101B155M32N1100		1.5	3.2±0.4	2.5±0.3	2.0	0.6±0.3	0.5
		2.2					
KTF101B135M43N1100		1.0					
KTF101B225M45N1100		2.2	4.5±0.4	3.2±0.4	2.8	0.6±0.3	1.0
KTF101B335M45N1100		3.3					
KTF101B685M55N1T00		6.8	5 7 + 0 /	5 0±0 4	2.8	0.8+0.5	2.0
KTF251B333M31N1T00		0.033	0.7 ±0.4	0.0±0.4	2.0	0.0±0.0	2.0
KTF251B473M31N1T00		0.033					
KTF251B683M31N1T00		0.047	3.2±0.2	1.6±0.2	1.8	0.5±0.3	0.3
KTF251B104M31N1T00	1	0.000					
KTF251B154M32N1T00	1	0.15					
KTF251B224M32N1T00	250	0.22	3.2 ± 0.4	2.5 ± 0.3	2.6	0.6±0.3	0.5
KTF251B334M32N1T00	250	0.33	0.2=011	2.020.0		0.020.0	0.0
KTF251B474M43N1T00		0.47					
KTF251B684M43N1T00	1	0.68	4.5±0.4	3.2±0.4	2.8	0.6±0.3	1.0
KTF251B105M55N1T00	1	1.0					
KTF251B155M55N1T00	1	1.5	5.7±0.4	5.0±0.4	2.8	0.8±0.5	2.0





♦FEATURES

- 1. Small size and large capacitance, high ripple current.
- 2. Temperature cycle: 1,000 cycles.
- 3. X7R temperature characteristics.
- 4. Excellent noise absorption.
- 5. For reflow soldering use.
- 6. Suitable for aluminum substrate.

♦APPLICATIONS

- 1. Smoothing circuit of switching mode AC-DC or DC-DC converter.
- 2. On-board power supply.
- 3. Noise suppressor for various kinds of equipments.

CUSTOM MADE PRODUCTS

We can offer custom made one element metal cap type capacitors for request of customers. Please contact us if you have questions for details.

CONSTRUCTION



RATINGS

1. Category Temperature Range	-55∼+125℃
2. Rated Voltage Range	25, 50, 100, 250Vdc
3. Rated Capacitance Range	1.5 to 47µF
4. Rated Capacitance Tolerance	M(±20%)
5. Temperature Characteristics	X7R
6. Rated Ripple Current	See No.5 on the following table

♦SPECIFICATIONS

No.	Items	Specification	Test Condition		
1	Withstand Voltage	No abnormality.	250% of rated voltage shall be applied for 5 seconds. (Only 250Vdc products : 475V)		
2	Insulation Resistance	100/Cr(M\Omega) or 4000(MΩ) whichever is less.	Rated voltage shall be applied for 60 ± 5 seconds at temperature $25\pm2^{\circ}$ C.		
3	Rated Capacitance	Within specified tolerance.	Cr≦10µF Cr>10µF		
			Temperature 25±2°C		
4	Dissipation Factor	5.0% maximum	Frequency 1±0.1kHz 120±12Hz		
			Voltage 1±0.2Vrms 0.5±0.2Vrms		
5	Rated Ripple Current	Size 55 Arms 3.0	10kHz~1MHz (sine curve) Ripple voltage Vp shall be less than the rated voltage.		



METAL CAP TYPE MULTILAYER CERAMIC CAPACITORS



♦SPECIFICATIONS

No.	Items	Specification	Test Condition
6	Temperature Cycle	Appearance : No visible damage. $\Delta C/C : \pm 15\%$ D.F. : To meet the initial specification. I.R. : To meet the initial specification.	StepTemperature (°C)(min.)1Min. Category temperature ±330±32Room temperature3 max.3Max. Category temperature ±330±34Room temperature3 max. <cycle>1000 cycles</cycle>
7	Humidity Load Life	Appearance : No abnormality. $\Delta C/C : \pm 20\%$ D.F. : 10% max. I.R. : 25/CR(M Ω) or 1000(M Ω) whichever is less.	Temperature : $40\pm 2^{\circ}$ CHumidity: 90 to 95%RHVoltage: Rated voltageTime: $500\pm_{0}^{24}$ hours
8	Endurance	Appearance : No abnormality. $\Delta C/C : \pm 20\%$ D.F. : 10% max. I.R. : 50/CR(M Ω) or 1000(M Ω) whichever is less.	Temperature : $85\pm2^{\circ}$ CVoltage: 200% of rated voltage.Time: $1000\pm_{0}^{48}$ hoursTemperature : $125\pm3^{\circ}$ CVoltage: Rated voltageTime: $1000\pm_{0}^{48}$ hours

*CR : Rated Capacitance(µF)

- Note of mountig for NTP series.1. The gap of capacitor and a substrate shall be the mounting face.
- 2. To prevent degredation of temperature cycling capability, if need to be careful about amount of solder that would not go into the inner side of terminations.



了 METAL CAP TYPE MULTILAYER CERAMIC CAPACITORS



♦PART NUMBERING SYSTEM



♦NTP SERIES STANDARD RATINGS

Maximum Dimensions(mm) Rated Capacitance Rated voltage Part Number ripple current (Vdc) (µF) w L Tmax. а . (Arms) KTP250B336M55BFT00 33 25 6.0±0.4 5.3±0.4 5.5 1.3±0.3 3.0 KTP250B476M55BFT00 47 KTP500B156M55BFT00 15 50 6.0±0.4 5.3±0.4 5.5 1.3±0.3 3.0 KTP500B226M55BFT00 22 KTP101B685M55BFT00 6.8 KTP101B106M55BFT00 100 10 6.0 ± 0.4 5.3±0.4 5.5 1.3±0.3 3.0 KTP101B156M55BFT00 15 1.5 2.2 KTP251B155M55BFT00 6.0±0.4 5.3±0.4 1.3±0.3 250 5.5 3.0 KTP251B225M55BFT00

♦DIMENSIONS





(Upgrade!)

♦FEATURES

- Small in size and wide capacitance range. Max. 33µF is available.
- 2. Temperature characteristic is X7R in EIA code.
- 3. Superior humidity characteristic and long life.
- 4. Excellent high frequency characteristic due to low ESR.
- 5. High rated ripple current.
- 6. 250Vdc items are available.
- 7. Resin(UL94 V-0) used for coating.
- 8. Pb-free design(also ceramic dielectric)

APPLICATIONS

- 1. Smoothing circuit of switching mode AC-DC or DC-DC converter.
- 2. Noise suppressor for various kinds of equipments.
- 3. By-pass or decoupling circuits.
- 4. Automotive equipments.

CONSTRUCTION



RATINGS

1. Category Temperature Range	-55 to +125℃
2. Rated Voltage Range	25, 50, 100, 250 Vdc
3. Rated Capacitance Range	0.1 to 33µF
4. Rated Capacitance Tolerance	M(±20%)
5. Temperature Characteristics	X7R
6. Rated Ripple Current	See No.5 on the following table

♦SPECIFICATIONS

No.	b. Items		Specification	Test Condition		on
1	Withstand Voltage	Between Terminals	No abnormality.	250% of rated voltage shall be applied for 5 second (Only 250Vdc products : 475V)		lied for 5 seconds.
		Terminals to Coating Resin				
2	Insulation Re	sistance	100/CR(MΩ) or 4000(MΩ) whichever is less.	Rated voltage temperature	age shall be applied for 60±5 seconds at ⊮e 25±2℃.	
3	Rated Capac	itance	Within specified tolerance.		Cr≦10µF Cr>10µF	
				Temperature	25±2℃	
4	Dissipation F	actor	5.0% maximum.	Frequency	1±0.1kHz	120±12Hz
				Voltage	1±0.2Vrms	0.5±0.2Vrms







♦SPECIFICATIONS

No.		Items	Specification				Test Condition		
5	Rated Ripple	Current	Size code Arms	32 0.3	43 0.8	55 1.0	10kHz to 1MHz (sine curve) Ripple voltage Vp shall be less than the rated voltage.		
6	Robustness	Tension	No visible damage	е.	1		The force applied shall be :		
	or Terminations						Lead φ (mm) Tensile(N) (sec.) 0.5 max. 5 10±1		
		Bending					Lead φ (mm) Bending(N) (kg) 0.5 max. 2.5 0.25 Time : 2times. 2 0		
7	Vibration Appearance : No abnormality. Capacitance : To meet the initial specification. D.F. : To meet the initial specifications.			Amplitude: 1.5mmFrequency range: 10-55-10Hz (1 min)Direction and time:2 hours each to X, Y, Z axis. Total 6 hours.					
8	Solderability Min. 75% of surface of the term shall be covered with new sold			e termir w solder	nation :	Solder Temperature : 235±5℃Dipping Time: 2±0.5 sec.Solder: H60A or H63A			
9	Resistance to Soldering Heat		Appearance : No abnormality. $\Delta C/C : \pm 15\%$ D.F. : Satisfy the initial spec.				Solder Temperature : 350±10°CDipping Time: 3±0.5 sec.Depth: 1.5 to 2mm		
10	0 Temperature Cycle		Appearance : No abnormality. $\Delta C/C : \pm 15\%$ D.F. : To meet the initial specification I.R. : To meet the initial specification		ation Ition	StepTemperature (°C)(min.)1Min. Category temperature ±330±32Room temperature3 max.3Max. Category temperature ±330±34Room temperature3 max.For 5 cycles for above temperature cycle.			
11	11 Humidity Load Life		Appearance : No abnormality. ΔC/C : ±20% D.F. : 10% maximum I.R. : 25/CR(MΩ) or 1000(MΩ) whichever is less.			5.	Temperature : $40\pm 2^{\circ}$ Humidity: 90 to 95%RHVoltage: Rated voltageTime: $500\pm_{0}^{24}$ hours		
12	12 Endurance		Appearance : No abnormality. $\Delta C/C : \pm 20\%$ D.F. : 10% maximum I.R. : 50/C _R (M Ω) or 1000(M Ω)			Temperature : $85\pm2^{\circ}$ CVoltage : 200% of rated voltage.Time : $1000\pm_{0}^{48}$ hoursTemperature : $125\pm3^{\circ}$ C			
			w	noneve	51 13 1655		Voltage : Rated voltage Time : 1000± ⁴⁸ / ₄ hours		

*CR : Rated Capacitance(µF)





◆PART NUMBERING SYSTEM



♦DIMENSIONS



♦NTD SERIES STANDARD RATINGS

David Marriel and	Rated voltage	Rated Capacitance		Maximum ripple current				
Part Number	(Vdc)	(μF)	Lmax.	Wmax.	Tmax.	F±0.8	¢d±0.05	(Arms)
KTD250B335M32A0T00		3.3	5.0	6.0	2.5	FO	0.5	0.2
KTD250B475M32A0T00	-	4.7	5.0	0.0	3.5	5.0	0.5	0.3
KTD250B685M43A0T00		6.8						
KTD250B106M43A0T00	25	10	6.5	6.5	4.0	5.0	0.5	0.8
KTD250B156M43A0T00	25	15						
KTD250B156M55A0T00		15						
KTD250B226M55A0T00		22	7.5	9.0	4.5	5.0	0.5	1.0
KTD250B336M55A0T00		33						
KTD500B105M32A0T00		1.0						
KTD500B155M32A0T00		1.5	5.0	60	35	5.0	0.5	03
KTD500B225M32A0T00		2.2	0.0	0.0	0.0	0.0	0.5	0.0
KTD500B335M32A0T00	50	3.3						
KTD500B475M43A0T00		4.7	65	6.5	4.0	5.0	0.5	0.8
KTD500B685M43A0T00		6.8	0.0					0.0
KTD500B106M55A0T00		10	75	90	45	5.0	0.5	10
KTD500B156M55A0T00		15	1.5	5.0	4.5	0.0	0.5	1.0
KTD101B334M32A0T00		0.33						
KTD101B474M32A0T00		0.47		6.0	3.5		0.5	
KTD101B684M32A0T00		0.68	50			5.0		03
KTD101B105M32A0T00		1	0.0			0.0		0.0
KTD101B155M32A0T00		1.5						
KTD101B225M32A0T00	100	2.2						
KTD101B155M43A0T00		1.5				5.0	0.5	
KTD101B225M43A0T00		2.2	65	65	4.0			0.8
KTD101B335M43A0T00		3.3	0.0	0.5	4.0	0.0	0.5	0.0
KTD101B475M43A0T00		4.7						
KTD101B685M55A0T00		6.8	7.5	9.0	4.5	5.0	0.5	1.0
KTD251B104M32A0T00		0.1						
KTD251B154M32A0T00		0.15	5.0	60	35	5.0	0.5	03
KTD251B224M32A0T00		0.22	0.0	0.0	0.0	0.0	0.5	0.0
KTD251B334M32A0T00	250	0.33						
KTD251B474M43A0T00	200	0.47	6.5	6.5	4.0	5.0	0.5	0.8
KTD251B684M43A0T00		0.68	0.0	0.5	4.0	5.0	0.5	0.0
KTD251B105M55A0T00		1	7.5	90	4.5	5.0	0.5	10
KTD251B155M55A0T00		1.5	1.5	3.0	4.0	5.0	0.5	1.0



MULTILAYER CERAMIC CHIP CAPACITORS

THC_{Series} / TMC_{Series} (High Reliability)



♦FEATURES

- 1. Small size and large capacitance, high ripple current.
- 2. Temperature characteristic is Y5U in EIA code.
- 3. Superior humidity characteristic and long life.
- 4. Excellent noise absorption.

♦APPLICATIONS

- 1. Smoothing circuit of small size DC-DC converter.
- 2. On-board power supply.
- 3. Noise suppressor for various kinds of equipments.
- 4. By-pass or decoupling circuits.

CONSTRUCTION



Tin Plating (21, 31, 32, 43size : For flow or reflow soldering) (55, 76size : For reflow soldering only) Silver (THC Series only) (All sizes : For reflow soldering only)

RATINGS

1. Category Temperature Range	-55 to +125℃
2. Rated Voltage Range	16, 25, 50, 100, 200Vdc
3. Rated Capacitance Range	0.047 to 100µF
4. Rated Capacitance Tolerance	M (±20%) , Z (±20%)
5. Temperature Characteristics	E (JIS)≒Y5U (EIA)
6. Rated Ripple Current	See No.5 on the following table

♦SPECIFICATIONS

No.	Items	Specification	Test Condition			
1	Withstand Voltage	No abnormality.	250% of rated voltage shall be applied for 5 seconds.			
2	Insulation Resistance	1000/Cr(MΩ) or 10000(MΩ) whichever is less.	Rated voltage shall be applied for 60±5 seconds at temperature 20±2°C.			
3	Rated Capacitance	Within specified tolerance.	Temperature : 20±2℃ Frequency : 1±0.1kHz Voltage : 1±0.2Vrms			
4	Dissipation Factor	5.0% maximum.	Temperature : 20±2°C Frequency : 1±0.1kHz Voltage : 1±0.2Vrms			
5	Rated Ripple Current	Size code 21 31 32 43 55 76 Arms 0.2 0.3 0.5 1.0 2.0 3.0	10kHz~1MHz (sine curve) Ripple voltage Vp shall be less than the rated voltage.			



THC Series / TMC Series

♦SPECIFICATIONS

No.	Items	Specification	Test Condition		
6	Adhesion	No visible damage.	Substrate 5N (0.51kgf) for 10±1 seconds Capacitor		
7	Bend strength of the face plating	Appearance : No visible damage. ΔC/C : ±15%	The substrate shall be bend by 1mm at a rate of 1mm/s for 5 seconds.		
8	Solderability	Min. 75% of surface of the termination shall be covered with new solder	Solder Temperature : 235±5°C Dipping Time : 2±0.5 sec. Solder : Eutectic solder containning Ag2.5 to 3wt%		
9	Resistance to Soldering Heat	Appearance : No visible damage. $\Delta C/C : \pm 15\%$ D.F. : To meet the initial specification. I.R. : To meet the initial specification.	Solder Temperature : 260±5°C Dipping Time : 2±0.5 seconds Solder : Eutectic solder containning Ag2.5 to 3wt%		
10	Temperature Cycle	Appearance : No visible damage. $\Delta C/C : \pm 15\%$ D.F. : To meet the initial specification. I.R. : To meet the initial specification.	StepTemperature (°C)(min.)1Min. Category temperature ±330±32Room temperature3 max.3Max. Category temperature ±330±34Room temperature3 max. <cycle>THC series : 5 cyclesTMC series : 100 cycles</cycle>		
11	Humidity Load Life	Appearance : No abnormality. $\Delta C/C : \pm 20\%$ D.F. : 7% maximum I.R. : 50/C _R (M Ω) or 1000(M Ω) whichever is less.	Temperature : $40\pm 2^{\circ}$ CHumidity: 90 to 95%RHVoltage: Rated voltageTime: $500\pm^{24}_{0}$ hours		
12	Endurance	Appearance : No abnormality. $\Delta C/C : \pm 20\%$ D.F. : 7% maximum I.R. : 100/CR(MΩ) or 1000(MΩ)	Temperature : $85\pm 2^{\circ}$ Voltage : 200% of rated voltage.Time : $1000\pm_{0}^{48}$ hours		
		whichever is less.	Temperature : $125\pm3^{\circ}$ CVoltage : Rated voltageTime : $1000\pm_{0}^{48}$ hours		

*CR : Rated Capacitance(µF)



♦PART NUMBERING SYSTEM



♦THC SERIES STANDARD RATINGS

DIMENSIONS



			Dimensions(mm)					
Part Number	Rated voltage (Vdc)	Rated Capacitance (µF)	L	w	Tmax.	a	Maximum ripple current (Arms)	Previous Part Number (Just for your reference)
KHC160E335M31N0T00		33						THCS30E1C335MTE
KHC160E475M31N0T00		4.7	3.2±0.2	1.6±0.2	1.6	0.5±0.3	0.3	THCS30E1C475MTF
KHC160E685M32N0T00		6.8		0.510.0			0.5	THCS40E1C685MTF
KHC160E106M32N0T00		10	3.2±0.2	2.5±0.2	2.0	0.6±0.3	0.5	THCS40E1C106MTF
KHC160E156M43N0T00	16	15	4 5 + 0 2	3 2+0 2	2.2	0.6+0.3	1.0	THCS50E1C156MTF
KHC160E226M43N0T00		22	4.5±0.5	5.2±0.2	2.2	0.010.3	1.0	THCS50E1C226MTF
KHC160E336M55N0T00		33	57+04	50+04	22	0.8+0.5	20	THCS60E1C336MTF
KHC160E476M55N0T00		47	0.1 = 0.1	0.02011		0.02010	2.0	THCS60E1C476MTF
KHC160E686M76N0T00		68	7.5±0.5	6.3±0.5	2.5	0.8±0.5	3.0	THCS70E1C686MTF
KHC160E107M76N0100		100			3.0			THCS/0E1C10/MTF
KHC250E334M21N0100		0.33	20+0.2	1 25+0 2	1.25	0.2+0.2	0.2	
KHC250E474M21N0T00		0.47	2.010.2	1.25±0.2	1.25	0.310.2	0.2	
KHC250E004M21N0T00		1.0						THCS20E1E004MTT
KHC250E155M31N0T00		1.5	32+02	16+02	16	0.5+0.3	0.3	THCS30E1E155MTF
KHC250E225M31N0T00		2.2	0.2=0.2			0.02010	0.0	THCS30E1E225MTF
KHC250E335M32N0T00	25	3.3		0.510.0				THCS40E1E335MTF
KHC250E475M32N0T00		4.7	3.2±0.2	2.5±0.2	2.0	0.6±0.3	0.5	THCS40E1E475MTF
KHC250E685M43N0T00		6.8			2.2			THCS50E1E685MTF
KHC250E106M43N0T00		10	4.5±0.3	3.2±0.2	2.2	0.6±0.3	1.0	THCS50E1E106MTF
KHC250E156M43N0T00		15			3.0			THCS50E1E156MTF
KHC250E226M55N0T00		22	57+04	50+04	2.2	0.8+0.5	2.0	THCS60E1E226MTF
KHC250E336M55N0T00		33		0.010	3.0	0.010.0	2.0	THCS60E1E336MTF
KHC250E476M76N0T00		47	7.5±0.5	6.3±0.5	3.0	0.8±0.5	3.0	THCS70E1E476MTF
KHC500E104M21N0100		0.1	20+0.2	1 25+0 2	1.25	0.2+0.2	0.2	
KHC500E224M21N0T00		0.13	2.0±0.2	1.25±0.2	1.25	0.5±0.2	0.2	THCS20E1H224MTF
KHC500F334M31N0T00		0.33						THCS30E1H334MTF
KHC500E474M31N0T00		0.47	3.2 ± 0.2	1.6±0.2	1.6	0.5±0.3	0.3	THCS30E1H474MTF
KHC500E684M31N0T00		0.68			-			THCS30E1H684MTF
KHC500E105M32N0T00		1.0			2.0			THCS40E1H105MTF
KHC500E155M32N0T00	50	1.5	3.2±0.2	2.5±0.2	2.0	0.6±0.3	0.5	THCS40E1H155MTF
KHC500E225M32N0T00		2.2			2.5			THCS40E1H225MTF
KHC500E335M43N0T00		3.3	4.5 ± 0.3	3.2 ± 0.2	2.2	0.6±0.3	1.0	THCS50E1H335MTF
KHC500E475M43N0T00		4.7			3.0			THCS50E1H475MTF
KHC500E685M55N0T00		6.8	E 7±0 4	5 0+0 4	2.2	0.0+0.5	2.0	THCS60E1H685MTF
KHC500E156M55N0T00		10	5.7±0.4	5.0±0.4	3.0	0.8±0.5	2.0	THCS60E1H156MTE
KHC500E226M76N0T00		22	7.5±0.5	63+05	2.5	0.8+0.5	3.0	THCS70E1H226MTF
KHC101E473M21N0T00		0.047	1.020.0	0.020.0	2.0	0.02010	0.0	THCS20E2A473MTF
KHC101E683M21N0T00		0.068	2.0 ± 0.2	1.25±0.2	1.25	0.3±0.2	0.2	THCS20E2A683MTF
KHC101E104M31N0T00		0.1						THCS30E2A104MTF
KHC101E154M31N0T00		0.15	3.2±0.2	1.6±0.2	1.6	0.5±0.3	0.3	THCS30E2A154MTF
KHC101E224M31N0T00		0.22						THCS30E2A224MTF
KHC101E334M32N0T00		0.33			2.0			THCS40E2A334MTF
KHC101E474M32N0T00	100	0.47	3.2 ± 0.2	2.5±0.2	0.5	0.6 ± 0.3	0.5	THCS40E2A474MTF
KHC101E084W32N0100		0.68			2.5			
KHC101E105WI45N0100		1.0	4 5+0 3	3 2+0 2	2.2	0.6+0.3	10	THCS50E2A105MTF
KHC101E225M43N0T00		22	4.5±0.5	5.2±0.2	3.0	0.0±0.0	1.0	THCS50E2A135MTF
KHC101E335M55N0T00		3.3			2.2			THCS60E2A335MTF
KHC101E475M55N0T00		4.7	5.7±0.4	5.0±0.4	3.0	0.8±0.5	2.0	THCS60E2A475MTF
KHC101E685M76N0T00		6.8	7.5±0.5	6.3±0.5	3.0	0.8±0.5	3.0	THCS70E2A685MTF
KHC201E473M31N0T00		0.047	3 2+0 2	16+02	16	0.5+0.3	03	THCS30E2D473MTF
KHC201E683M31N0T00		0.068	0.2-0.2	1.0-0.2	1.0	0.0±0.0	0.0	THCS30E2D683MTF
KHC201E104M32N0T00		0.1	0.010.0	0.510.0	2.0	0.0100	0.5	THCS40E2D104MTF
KHC201E154M32N0T00		0.15	3.2±0.2	2.5±0.2	25	0.6±0.3	0.5	THCS40E2D154MTF
KHC201E334M42N0T00	200	0.22			2.5			
KHC201E474M43N0T00	200	0.33	4.5±0.3	3.2±0.2	3.0	0.6±0.3	1.0	THCS50E2D334WTF THCS50E2D474MTF
KHC201E684M55N0T00		0.68			2.2			THCS60E2D684MTF
KHC201E105M55N0T00		1.0	5.7±0.4	5.0±0.4	3.0	0.8±0.5	2.0	THCS60E2D105MTF
KHC201E155M76N0T00		1.5	7 F±0 F	6 2±0 5	2.5	0.0+0.5	2.0	THCS70E2D155MTF
KHC201E225M76N0T00		2.2	1.5±0.5	0.3±0.5	3.0	0.0±0.5	3.0	THCS70E2D225MTF





♦PART NUMBERING SYSTEM



♦DIMENSIONS



◆TMC SERIES STANDARD RATINGS

Dent Normh en	Rated voltage	Rated Capacitance	Dimensions(mm)				Maximum ripple current	Previous Part Number
Part Number	(Vdc)	(μF)	L	w	Tmax.	а	(Arms)	(Just for your reference)
KMC250E684M31N0T00		0.68						TMCS30E1E684MTF
KMC250E105M31N0T00	-	1	3.2±0.2	1.6±0.2	1.6	0.4±0.2	0.3	TMCS30E1E105MTF
KMC250E155M31N0T00		1.5						TMCS30E1E155MTF
KMC250E225M32N0T00	25	2.2	3 2+0 2	25+02	22	05+02	0.5	TMCS40E1E225MTF
KMC250E335M32N0T00	25	3.3	5.2±0.2	2.0±0.2	2.2	0.5±0.2	0.5	TMCS40E1E335MTF
KMC250E475M43N0T00		4.7			25			TMCS50E1E475MTF
KMC250E685M43N0T00		6.8	4.5±0.3	3.2±0.2	2.5	0.5±0.3	1.0	TMCS50E1E685MTF
KMC250E106M43N0T00		10			3.0			TMCS50E1E106MTF
KMC500E334M31N0T00		0.33	32+02	16+02	16	04+02	0.3	TMCS30E1H334MTF
KMC500E474M31N0T00		0.47	0.2±0.2	1.0±0.2	1.0	0.4±0.2	0.0	TMCS30E1H474MTF
KMC500E684M32N0T00		0.68			22	0.5±0.2	0.5	TMCS40E1H684MTF
KMC500E105M32N0T00	50	1.0	3.2±0.2	2.5±0.2	2.2			TMCS40E1H105MTF
KMC500E155M32N0T00		1.5			2.5			TMCS40E1H155MTF
KMC500E225M43N0T00		2.2	4.5±0.3	3.2±0.2	25		1.0	TMCS50E1H225MTF
KMC500E335M43N0T00		3.3			2.0	0.5±0.3		TMCS50E1H335MTF
KMC500E475M43N0T00		4.7			3.0			TMCS50E1H475MTF
KMC101E104M31N0T00		0.1	3.2±0.2	1.6±0.2 2.5±0.2	16	04+02	0.3	TMCS30E2A104MTF
KMC101E154M31N0T00		0.15						TMCS30E2A154MTF
KMC101E224M32N0T00		0.22			2.2	0.5±0.2		TMCS40E2A224MTF
KMC101E334M32N0T00	100	0.33	3.2±0.2					TMCS40E2A334MTF
KMC101E474M32N0T00		0.47						TMCS40E2A474MTF
KMC101E684M43N0T00		0.68			2.5		1.0	TMCS50E2A684MTF
KMC101E105M43N0T00		1.0	4.5±0.3	3.2±0.2		0.5±0.3		TMCS50E2A105MTF
KMC101E155M43N0T00		1.5			3.0			TMCS50E2A155MTF
KMC201E333M31N0T00		0.033	3.2±0.2	1.6±0.2	1.6	0.4±0.2	0.3	TMCS30E2D333MTF
KMC201E473M31N0T00		0.047			-			IMCS30E2D473MTF
KMC201E683M32N0T00	200	0.068			2.2			IMCS40E2D683MTF
KMC201E104M32N0T00		0.1	3.2 ± 0.2	2.5±0.2		0.5 ± 0.2	0.5	IMCS40E2D104MTF
KMC201E154M32N0T00		0.15			2.5			TMCS40E2D154MTF
KMC201E224M43N0T00		0.22	45100		2.5	0.510.6		TMCS50E2D224MTF
KMC201E334M43N0T00		0.33	4.5±0.3	3.2±0.2		0.5±0.3	1.0	IMCS50E2D334MTF
KMC201E474M43N0T00		0.47			3.0			IMCS50E2D474MTF



METAL CAP TYPE MULTILAYER CERAMIC CAPACITORS

THP Series / TMP Series (High Reliability)





♦FEATURES

- 1. Small size and large capacitance, high ripple current.
- 2. Excellent temperature cycle durability and most suitable for aluminum substrate.
- 3. Y5U temperature characteristics.
- 4. Excellent noise absorption.
- 5. For reflow soldering use.
- 6. Suitable for aluminum substrate.

APPLICATIONS

- 1. Smoothing circuit of switching mode AC-DC or DC-DC converter.
- 2. On-board power supply.
- 3. Noise suppressor for various kinds of equipments.

CUSTOM MADE PRODUCTS

We can offer custom made one element metal cap type capacitors for request of customers. Please contact us if you have questions for details.

CONSTRUCTION



RATINGS

1. Category Temperature Range	-55~+125℃
2. Rated Voltage Range	16, 25, 50, 100, 200Vdc
3. Rated Capacitance Range	0.45 to 200μF
4. Rated Capacitance Tolerance	M(±20%), Z(± ⁸⁰ ₂₀ %)
5. Temperature Characteristics	E(JIS)≒Y5U(EIA)
6. Rated Ripple Current	See No.5 on the following table

♦ SPECIFICATIONS

No.	Items	Specification	Test Condition		
1	Withstand Voltage	No abnormality.	250% of rated voltage shall be applied for 5 seconds.		
2	Insulation Resistance	1000/Cr(M Ω) or 10000(M Ω) whichever is less.	Rated voltage shall be applied for 60 ± 5 seconds at temperature 20 ± 2 °C.		
3	Rated Capacitance	Within specified tolerance.	Temperature : 20±2℃ Frequency : 1±0.1kHz (≧100µF, 120Hz) Voltage : 1±0.2Vrms		
4	Dissipation Factor	5.0% maximum	Temperature : 20±2℃ Frequency : 1±0.1kHz (≧100µF, 120Hz) Voltage : 1±0.2Vrms		
5	Rated Ripple Current	Size 43 55 76 Arms 1.5 3.0 4.0	10kHz~1MHz (sine curve) Ripple voltage Vp shall be less than the rated voltage.		



METAL CAP TYPE MULTILAYER CERAMIC CAPACITORS

THP Series / TMP Series

SPECIFICATIONS

No.	Items	Specification	Test Condition			
6	Temperature Cycle	Appearance : No visible damage. $\Delta C/C : \pm 15\%$ D.F. : To meet the initial specification. I.R. : To meet the initial specification.	StepTemperature (°C)(min.)1Min. Category temperature ±330±32Room temperature3 max.3Max. Category temperature ±330±34Room temperature3 max. <cycle>THP series : 100 cyclesTMP series : 500 cycles</cycle>			
7	Humidity Load Life	Appearance : No abnormality. $\Delta C/C : \pm 20\%$ D.F. : 7% max. I.R. : 50/C _R (M Ω) or 1000(M Ω) whichever is less.	Temperature : $40\pm 2^{\circ}$ CHumidity: 90 to 95%RHVoltage: Rated voltageTime: $500\pm_{0}^{24}$ hours			
8	Endurance	Appearance : No abnormality. $\Delta C/C : \pm 20\%$ D.F. : 7% max. I.R. : 100/CR(MΩ) or 1000(MΩ)	Temperature : $85\pm 2^{\circ}$ CVoltage : 200% of rated voltage.Time : $1000\pm_{0}^{48}$ hours			
		whichever is less.	Voltage : Rated voltage Time : 1000± ⁴ ⁰ ₀ hours			

*CR : Rated Capacitance(µF)

♦Note of mountig for THP series.

- 1. The face of wider gap between a capacitor and a substrate shall be the mounting face.
- 2. To prevent degredation of temperature cycling capability, if need to be careful about amount of solder that would not go into the inner side of terminations.



♦Note:

Single capacitor with metal cap is available upon request. Please consult us for details.





PART NUMBERING SYSTEM



THP SERIES STANDARD RATINGS

Dimensions(mm) Rated voltage Rated Capacitance Maximum ripple current Previous Part Number Part Number (Vdc) (µF) (Arms) (Just for your reference) L w Tmax а KHP160E336M435AT00 33 THP50E1C336MT502 4.8±0.4 3.5±0.4 5.5 1.3±0.3 1.5 THP50E1C476MT502 KHP160E476M435AT00 47 KHP160E686M555AT00 5.0 16 THP60E1C686MT502 68 6.0±0.4 5.0±0.4 1.3±0.3 3.0 THP60E1C107MT502 KHP160E107M555AT00 100 56 KHP160E157M765BT00 150 THP70E1C157MT502 7.8±0.5 6.6±0.5 1.5±0.3 4.0 6.5 KHP160E207M765BT00 200 THP70E1C207MT502 KHP250E156M435AT00 15 THP50E1E156MT502 4.8±0.4 3.5±0.3 1.3±0.3 5.5 1.5 KHP250E206M435AT00 20 THP50E1E206MT502 KHP250E336M555AT00 25 33 THP60E1E336MT502 4.5 KHP250E476M555AT00 47 60+045.0±0.4 1.3±0.3 3.0 THP60E1E476MT502 KHP250E686M555AT00 68 5.6 THP60E1E686MT502 KHP250E107M765BT00 100 78+05 6.6±0.5 6.5 1.5±0.3 40 THP70E1E107MT502 4.5 KHP500E455M435AT00 THP50E1H455MT502 4.8±0.4 3.5±0.3 5.5 1.3±0.3 1.5 KHP500E685M435AT00 6.8 THP50E1H685MT502 KHP500E106M555AT00 THP60E1H106MT502 10 4.5 KHP500E156M555AT00 50 15 6.0 ± 0.4 5.0±0.4 1.3±0.3 3.0 THP60E1H156MT502 KHP500E226M555AT00 22 5.6 THP60E1H226MT502 KHP500E336M765BT00 THP70E1H336MT502 33 6.6 ± 0.5 7.8 ± 0.5 6.5 1.5 ± 0.3 4.0 KHP500E476M765BT00 47 THP70E1H476MT502 KHP101E155M435AT00 1.5 THP50E2A155MT502 KHP101E205M435AT00 2.0 4.8±0.4 3.5±0.3 5.5 1.3±0.3 1.5 THP50E2A205MT502 KHP101E305M435AT00 3.0 THP50E2A305MT502 100 KHP101E475M555AT00 4.7 THP60E2A475MT502 45 KHP101E685M555AT00 6.8 6.0±0.4 5.0±0.4 1.3±0.3 3.0 THP60E2A685MT502 KHP101E106M555AT00 5.6 THP60E2A106MT502 10 KHP101E156M765BT00 7.8±0.5 6.6±0.5 1.5±0.3 4.0 THP70E2A156MT502 15 6.5 KHP201E454M435AT00 0.45 THP50E2D454MT502 KHP201E684M435AT00 4.8±0.4 3.5±0.3 5.5 1.3±0.3 1.5 THP50E2D684MT502 0.68 KHP201E105M435AT00 THP50E2D105MT502 1.0 KHP201E155M555AT00 200 4.5 THP60E2D155MT502 1.5 6.0±0.4 5.0±0.4 1.3±0.3 3.0 KHP201E225M555AT00 THP60E2D225MT502 2.2 5.6 KHP201E335M765BT00 THP70E2D335MT502 3.3 7.8±0.5 66 ± 05 65 1.5±0.3 4.0 KHP201E475M765BT00 THP70E2D475MT502 4.7

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METAL CAP TYPE MULTILAYER CERAMIC CAPACITORS



NIPPON CHEMI-CON

♦PART NUMBERING SYSTEM



◆TMP SERIES STANDARD RATINGS

Dani Murahan	Rated voltage Rated Capacitance			Dimens	ions(mm)	Maximum ripple current	Previous Part Number	
Part Number	(Vdc)	(μ F)	L	w	Tmax.	а	(Arms)	(Just for your reference)
KMP250E336M555ET00		33	6 4±0 4	5 0±0 4	5.0	1 2 - 0 2	2.0	TMP60E1E336MT502
KMP250E476M555ET00	25	47	0.4±0.4	5.0±0.4	5.0	1.3±0.3	3.0	TMP60E1E476MT502
KMP250E686M765ET00	25	68	0.0+0.5	0.0+0.5	0.5	1 5 - 0 2	4.0	TMP70E1E686MT502
KMP250E107M765ET00		100	8.2±0.5	6.6±0.5	0.0	1.5±0.5	4.0	TMP70E1E107MT502
KMP500E106M555ET00		10						TMP60E1H106MT502
KMP500E156M555ET00	50	15	6.4±0.4	5.0±0.4	5.0	1.3±0.3	3.0	TMP60E1H156MT502
KMP500E226M555ET00		22						TMP60E1H226MT502
KMP500E336M765ET00		33	8.2±0.5	6.6±0.5	6.5	1.5±0.3	4.0	TMP70E1H336MT502
KMP500E476M765ET00		47						TMP70E1H476MT502
KMP101E475M555ET00		4.7	1 2 + 0 2	2.0	TMP60E2A475MT502			
KMP101E685M555ET00	100	6.8	0.4±0.4	5.0±0.4	5.0	1.5±0.5	3.0	TMP60E2A685MT502
KMP101E106M765ET00	100	10	0.0+0.5		0.5	4 5 + 0 2	4.0	TMP70E2A106MT502
KMP101E156M765ET00		15	8.2±0.5	6.6±0.5	0.0	1.5±0.3	4.0	TMP70E2A156MT502
KMP201E155M555ET00		1.5	C 4±0 4	5 0+0 4	5.0	4 2+0 2	2.0	TMP60E2D155MT502
KMP201E225M555ET00		2.2	6.4±0.4	5.0±0.4	5.0	1.3 ± 0.3	3.0	TMP60E2D225MT502
KMP201E335M765ET00	200	3.3	0 0±0 F	C C+O F	6 F	1 5 + 0 2	4.0	TMP70E2D335MT502
KMP201E475M765ET00		4.7	0.2±0.5	6.6±0.5	6.5	1.5±0.3	4.0	TMP70E2D475MT502

DIMENSIONS





THDseries RoHS

♦FEATURES

- 1. Small size and large capacitance, high ripple current.
- 2. Temperature characteristic is Y5U in EIA code.
- 3. Superior humidity characteristic and long life.
- 4. Excellent noise absorption.
- 5. Resin(UL94 V-0) used for coating.

APPLICATIONS

- 1. Automotive equipments.
- 2. Smoothing circuit of switching mode AC-DC or DC-DC converter.
- 3. Noise suppressor for various kinds of equipments.
- 4. By-pass or decoupling circuits.

CONSTRUCTION



♦RATINGS

1. Category Temperature Range	-55 to +125℃
2. Rated Voltage Range	16, 25, 50, 100, 250 Vdc
3. Rated Capacitance Range	0.1 to 680µF
4. Rated Capacitance Tolerance	M(±20%), Z(± ⁸⁰ ₂₀ %)
5. Temperature Characteristics	E(JIS)≒Y5U(EIA)
6. Rated Ripple Current	See No.5 on the following table

♦SPECIFICATIONS

No.	Items		Specification	Test Condition		
1	Withstand Between Voltage Terminals		No abnormality.	250% of rated voltage shall be applied for 5 seconds.		
		Terminals to Coating Resin				
2	Insulation Resistance		1000/CR(M Ω) or 10000(M Ω) whichever is less.	Rated voltage shall be applied for 60 ± 5 seconds at temperature 20 ± 2 °C.		
3	Rated Capacitance		Within specified tolerance.	Temperature : 20±2℃ Frequency : 1±0.1kHz(≧100µF,120Hz) Voltage : 1±0.2Vrms		
4	Dissipation Factor		5.0% maximum.	Temperature : 20±2℃ Frequency : 1±0.1kHz(≧100µF,120Hz) Voltage : 1±0.2Vrms		





THD_{Series}

♦SPECIFICATIONS

5 Rated Rippie Current Size code 32 43 55 76 80 90 90 Arms 0.3 0.8 h.0 1.5 2.0 3.0 4.0 10kHz to 1MHz (sine curve) Rippie voltage Vp shall be less than the rated voltage. 6 Robustness of Terminations Tension Tension No visible damage. The force applied shall be : 8 Pending Bending The force applied of angle (mm) Tensie(N) (kg) 0.5 max. 10 10±1 0.6 to 0.8 max. 10 10±1 7 Vibration Appearance : No abnormality. Capacitance : To meet the initial specification. D.F.: To meet the initial specification. Solder Temperature : 255-10Hz (1 min) Directon and time : 2 hours each to X.Y.Z axis. Total 6 hours. 8 Solderability Appearance : No abnormality. Appearance : No abnormality. D.F.: Satisfy the initial specification. D.F.: To meet the initial specification D.F.: To meet the initial specif	No.	Items		Specification	Test Condition				
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6 of Terminations Tension of Terminations No visible damage. The force applied shall be :				Arms 0.3 0.8 1.0 1.5 2.0 3.0 4.0	Ripple voltage Vp shall be less than the rated voltage.				
Understand Image: Constraint of the section of the sectin of the section of the section of the section of the	6	Robustness	Tension	No visible damage.	The force applied shall be :				
Image: Section of the section of t		Terminations			Lead ϕ (mm)Tensile(N)(sec.)				
Image: Second					0.5 max. 5 10±1				
Bending Lead ϕ (mm) Bending(N) (kg) 0.5 max. 2.5 0.25 0.6 to 0.8 max. 5 0.51 Time : 2 times. Time : 2 times. 7 Vibration Appearance : No abnormality. Capacitance : To meet the initial specification. Amplitude :: 1.5mm Frequency range :: 10-55-10Hz (1 min) Direction and time :: 2 hours each to X, Y, Z axis. Total 6 hours. 8 Solderability Min. 75% of surface of the termination shall be covered with new solder. Solder Temperature : 236±5°C Dipping Time :: 2±0.5 sec. Solder :: H60A or H63A 9 Resistance to Soldering Heat Appearance : No abnormality. $\Delta CC : \pm 15\%$ D.F. : Satisfy the initial spec. Solder Temperature : 360±10°C Dipping Time :: 3±0.5 sec. Depth :: 1.5 to 2mm 10 Temperature Cycle Appearance : No abnormality. $\Delta CC : \pm 15\%$ D.F. : To meet the initial specification I.R. : SolCs(MQ) or 1000(MQ) whichever is less. Temperature : 40±2°C Humidity = 0 to 95% RH Voltage :: Rated voltage Time :: 500± ² ₀ hours 12 Endurance Appearance : No abnormality. $\Delta CC : \pm 20\%$ D.F. : 7% maximum I.R. : 50/Cs(MQ) or 1000(MQ) whichever is less. Temperature : 85±2°C Voltage :: 200% of rated voltage. Time :: 1000± ⁴ % hours 12 Endurance Appearance : No abnormality. $\Delta CC : \pm 20\%$ Temperature : 125±3°C					0.6 to 0.8 max. 10 10±1				
1 Lead et (m)			Bending						
1 Los base Los base Los base Los base Los base Los base 7 Vibration Appearance : No abnormality. Capacitance : To meet the initial specification. D.F. : To meet the initial specification. D.F. : To meet the initial specification. Amplitude : 1.5mm Frequency range : 10-55-10Hz (1 min) Direction and time : 2 hours each to X, Y, Z axis. Total 6 hours. 8 Solderability Min. 75% of surface of the termination shall be covered with new solder. Solder Temperature : 235±5°C Dipping Time : 2±0.5 sec. Solder : H60A or H63A 9 Resistance to Soldering Heat Appearance : No abnormality. ΔC/C : ±15% D.F. : Satisfy the initial spec. Solder Temperature : 350±10°C Dipping Time : 3±0.5 sec. Depth : 1.5 to 2mm 10 Temperature Cycle Appearance : No abnormality. ΔC/C : ±15% D.F. : To meet the initial specification I.R. : To baboe temperature dot dot babee temperature dot			-		Lead ϕ (mm) Bending(N) (kg)				
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12EnduranceAppearance : No abnormality. $\Delta C/C : \pm 20\%$ Temperature : $85\pm 2^{\circ}C$ Voltage : 200% of rated voltage. Time : $1000\pm_{0}^{24}$ hours12EnduranceAppearance : No abnormality. $\Delta C/C : \pm 20\%$ D.F. : 7% maximum I.R. : $100/C_R(M\Omega)$ or $1000(M\Omega)$ whichever is less.Temperature : $85\pm 2^{\circ}C$ Voltage : 200% of rated voltage. Time : $1000\pm_{0}^{48}$ hours	11	Humidity Load Life		Appearance : No abnormality.	Lumidity $100 \text{ to } 05\%$ PH				
12EnduranceAppearance : No abnormality. $\Delta C/C : \pm 20\%$ $D.F. : 7\%$ maximum $I.R. : 100/C_R(M\Omega)$ or 1000(MΩ) whichever is less.Temperature : $85\pm 2^{\circ}C$ Voltage : 200% of rated voltage. Time : $1000\pm_{0}^{48}$ hoursTemperature : $125\pm 3^{\circ}C$				D E : 7% maximum	Voltage : Rated voltage				
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12 Endurance Appearance : No abnormality. Temperature : 85±2°C 0.F. : 7% maximum D.F. : 7% maximum Time : 1000± ⁴⁸ / ₀ hours 1.R. : 100/CR(MΩ) or 1000(MΩ) whichever is less. Temperature : 125±3°C				whichever is less.					
12EnduranceAppearance : No abnormality. $\Delta C/C : \pm 20\%$ D.F. : 7% maximum I.R. : 100/CR(M Ω) or 1000(M Ω) whichever is less.Temperature : $85\pm2^{\circ}C$ Voltage : 200% of rated voltage. Time : $1000\pm_{0}^{48}$ hoursTemperature : $125\pm3^{\circ}C$									
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$\begin{array}{c} \text{I.R. : 100/CR(M\Omega) or 1000(M\Omega)} \\ \text{whichever is less.} \end{array}$				$\Delta C/C : \pm 20\%$	Voltage : 200% of rated voltage.				
whichever is less. Temperature : 125±3°C		U.F		$\square \square $					
				whichever is less.	Temperature : 125±3°C				
Voltage : Rated voltage					Voltage : Rated voltage				
Time : 1000± ⁴⁸ ₀ hours					Time : $1000\pm_{0}^{48}$ hours				

*CR : Rated Capacitance(µF)

◆PART NUMBERING SYSTEM

 $\stackrel{1}{\textbf{K}}\stackrel{2}{\textbf{HD}}\stackrel{3}{\textbf{500}}\stackrel{4}{\textbf{500}}\stackrel{5}{\textbf{E}}\stackrel{7}{\textbf{106}}\stackrel{8}{\textbf{M}}\stackrel{10}{\textbf{555}}\stackrel{11}{\textbf{555}}\stackrel{14}{\textbf{555}}\stackrel{15}{\textbf{100}}\stackrel{16}{\textbf{T}}\stackrel{17}{\textbf{000}}$



♦DIMENSIONS

≥

15min.

Crimped lead 32~76 size



Straight lead

THD_{Series}

♦THD SERIES STANDARD RATINGS

Devi Nevel en	Rated voltage (Vdc)	Rated Capacitance	ated Capacitance Dimensions (mm)				Maximum ripple current	Previous Part Number	
Part Number		(μ F)	Lmax.	Wmax.	Tmax.	F±0.8	φ d ±0.05	(Arms)	(Just for your reference)
KHD160E685M32A0T00		6.8	5.0	6.5	25	5.0	0.5	0.2	THD21E1C685MT
KHD160E106M32A0T00		10	5.0	0.0	3.5	5.0	0.5	0.3	THD21E1C106MT
KHD160E156M43A0T00		15	6.5	7.5	4.0	5.0	0.5	0.8	THD30E1C156MT
KHD160E226M43A0100		22							THD30E1C226MT
KHD160E476M55A0T00		47	8.0	9.0	4.5	5.0	0.5	1.0	THD31E1C476MT
KHD160E686M76A0T00	16	68	10.0	11 5	4 5	5.0	0.5	1 5	THD41E1C686MT
KHD160E107M76A0T00		100	10.0	11.5	4.5	5.0	0.5	1.5	THD41E1C107MT
KHD160E157M80A0B00		150	13.5	15.0	5.0	10.0	0.6	2.0	THD51E1C157M
KHD160E227W80A0B00 KHD160E337M90C0B00		330			5.5				THD5TETC227M THD60E1C337M
KHD160E477M90C0B00		470	22.5	20.0	6	20.0	0.8	3.0	THD60E1C477M
KHD160E687M99C0B00		680	28.5	20.0	7.5	25.0	0.8	4.0	THD61E1C687M
KHD250E335M32A0T00		3.3	5.0	6.5	3.0	5.0	0.5	0.3	THD21E1E335MT
KHD250E475M32A0100 KHD250E685M43A0T00		4.7			3.5				THD21E1E475MT
KHD250E106M43A0T00		10	6.5	7.0	3.5	5.0	0.5	0.8	THD30E1E106MT
KHD250E156M43A0T00		15			4.0				THD30E1E156MT
KHD250E226M55A0T00		22	7.5	9.0	4.0	5.0	0.5	1.0	THD31E1E226MT
KHD250E336M55A0T00	25	<u>33</u> 47	10.0	11.5	4.5	5.0	0.5	15	THD31E1E336MT
KHD250E686M80A0B00	1	68	10.0	11.0	5.0	0.0	0.5	1.0	THD51E1E686M
KHD250E107M80A0B00		100	13.5	15.0	5.5	10.0	0.6	2.0	THD51E1E107M
KHD250E157M90C0B00		150	22.5	20.0	6.0	20.0	0.8	3.0	THD60E1E157M
KHD250E227M90C0B00		220	-	-		-			THD61E1E227M
KHD250E477M99C0B00		470	28.5	20.0	7.5	25.0	0.8	4.0	THD61E1E477M
KHD500E105M32A0T00		1.0			2.0				THD21E1H105MT
KHD500E155M32A0T00		1.5	5.0	6.5	5.0	5.0	0.5	0.3	THD21E1H155MT
KHD500E225M32A0T00 KHD500E335M43A0T00		2.2			3.5				THD30E1H335MT
KHD500E475M43A0T00		4.7	6.5	7.0	4.0	5.0	0.5	0.8	THD30E1H475MT
KHD500E685M55A0T00		6.8	7.5	9.0	4.0		0.5	1.0	THD31E1H685MT
KHD500E106M55A0T00	50	10			4.5	5.0			THD31E1H106MT
KHD500E156M55A0100 KHD500E226M76A0T00	50	15	10.0	11.5	4.5	5.0	0.5	15	THD31E1H156M1 THD41F1H226MT
KHD500E336M80A0B00		33	13.5	15.0	5.0	10.0	0.6	2.0	THD51E1H336M
KHD500E476M90C0B00		47		20.0	6.0	20.0	0.8	3.0	THD60E1H476M
KHD500E686M90C0B00		68	22.5						THD60E1H686M
KHD500E157M99C0B00		150							THD61E1H157M
KHD500E227M99C0B00		220	28.5	20.0	7.5	25.0	0.8	4.0	THD61E1H227M
KHD101E334M32A0T00		0.33			3.0		0.5 0.5	0.3	THD21E2A334MT
KHD101E474M32A0T00		0.47	5.0	6.5	2.5	5.0			
KHD101E105M43A0T00	-	1.0			3.5				THD30E2A105MT
KHD101E155M43A0T00		1.5	1.5 6.5 2.2	7.0	3.5 4.0	5.0			THD30E2A155MT
KHD101E225M43A0T00		2.2							THD30E2A225MT
KHD101E335M55A0T00		3.3	7.5	9.0	4.0	5.0	0.5	1.0	
KHD101E685M76A0T00	100	6.8	10.0	11.5	4.5	5.0	0.5	1.5	THD41E2A685MT
KHD101E106M80A0B00	1	10	12.5	15.0	5.0	10.0	0.6	2.0	THD51E2A106M
KHD101E156M80A0B00		15	13.5	- 13.0	5.0	10.0	0.0	2.0	THD51E2A156M
KHD101E226M90C0B00		22	22.5	20.0	6.0	20.0	0.8	3.0	THD60E2A226M
KHD101E336M90C0B00 KHD101E476M99C0B00		47	6.5	20.0		25.0 5.0	0.8		THD60E2A336M THD61E2A476M
KHD101E686M99C0B00		68			7.5			4.0	THD61E2A686M
KHD101E107M99C0B00		100							THD61E2A107M
KHD251E104M43A0T00	1	0.1			25			0.8	
KHD251E224M43A0T00		0.13			3.5				THD30E2E224MT
KHD251E334M43A0T00]	0.33			4.0				THD30E2E334MT
KHD251E474M55A0T00		0.47	7.5	9.0	4.0	5.0	0.5	1.0	THD31E2E474MT
KHD251E684M55A0T00		0.68			4.5				THD31E2E684MT
KHD251E105M/6A0100 KHD251E155M76A0T00	250	1.0	10.0	11.5	4.5	5.0	0.5	1.5	THD41E2E105MT
KHD251E225M80A0B00		2.2	13.5	15.0	5.0	10.0	0.6	2.0	THD51E2E225M
KHD251E335M90C0B00		3.3	22.5	20.0	6.0	20.0	0.8	3.0	THD60E2E335M
KHD251E475M90C0B00		4.7 6.8	28.5	20.0			0.0		THD60E2E475M
KHD251E106M99C0B00		10		20.0	7.5	25.0	0.8	4.0	THD61E2E106M
KHD251E156M99C0B00		15						THD61E2E156M	

Temperature and DC voltage Characteristics

NIPPON CHEMI-CON



Frequency Characteristics

